3.3V CMOS 12-BIT TO 24-BIT REGISTERED BUS EXCHANGER WITH 3-STATE OUTPUTS AND BUS-HOLD

IDT74ALVCHR162269A

FEATURES:

- 0.5 MICRON CMOS Technology
- Typical $t_{SK(o)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- V_{CC} = 3.3V ± 0.3V, Normal Range
- V_{CC} = 2.7V to 3.6V, Extended Range
- V_{CC} = 2.5V ± 0.2V
- CMOS power levels (0.4μ W typ. static)
- Rail-to-Rail output swing for increased noise margin
- Available in SSOP, TSSOP, and TVSOP packages

DRIVE FEATURES:

- Balanced Output Drivers: ±12mA
- Low Switching Noise

APPLICATIONS:

- 3.3V high speed systems
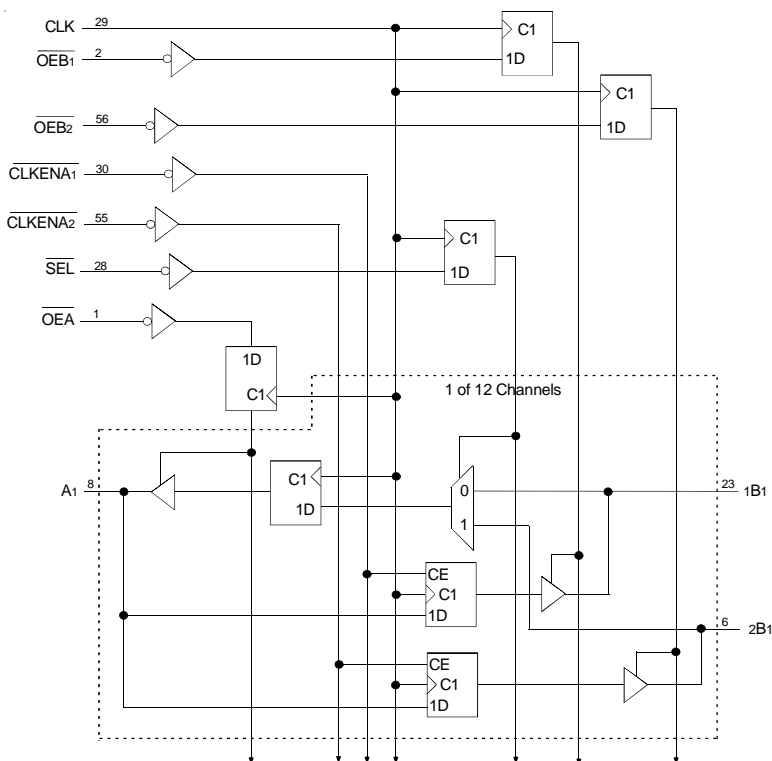- 3.3V and lower voltage computing systems

DESCRIPTION:

This 12-bit to 24-bit registered bus exchanger is used in applications in which two separate ports must be multiplexed onto, or demultiplexed from, a single port. It is particularly suitable as an interface between synchronous DRAMs and high-speed microprocessors.

Data is stored in the internal B-port registers on the low-to-high transition of the clock (CLK) input when the appropriate clock-enable ($\overline{CLKENA}$) inputs are low. Proper control of these inputs allows two sequential 12-bit words to be presented as a 24-bit word on the B-port. For data transfer in the B-to-A direction, a single storage register is provided. The select $\overline{SEL}$ line selects 1B or 2B data for the A outputs. The register on the A output permits the fastest possible data transfer, thus extending the period during which the data is valid on the bus. The control terminals are registered so that all transactions are synchronous with CLK. Data flow is controlled by the active-low output enables ($\overline{OEA}$, $\overline{OEB1}$ and $\overline{OEB2}$).

The ALVCHR162269A has series resistors in the device output structure which will significantly reduce line noise when used with light loads. This driver has been designed to drive ±12mA at the designated threshold levels.

The ALVCHR162269A has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.
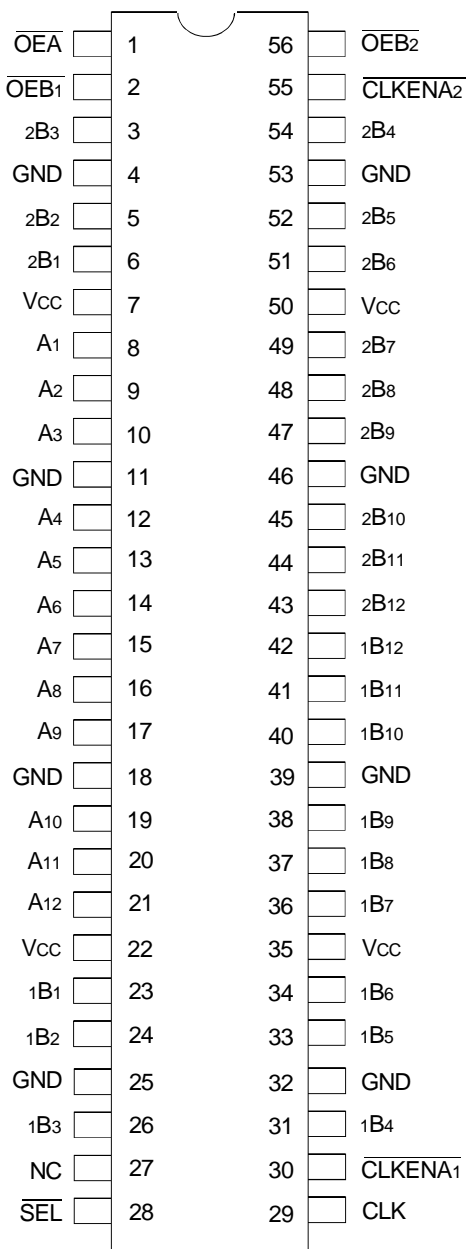
FUNCTIONAL BLOCK DIAGRAM

INDUSTRIAL TEMPERATURE RANGE

MARCH 1999

DSC-4239/1

PIN CONFIGURATION

$\overline{OEA}$	1	56	$\overline{OEB}_2$
$\overline{OEB}_1$	2	55	$\overline{CLKENA2}$
$_2B_3$	3	54	$_2B_4$
GND	4	53	GND
$_2B_2$	5	52	$_2B_5$
$_2B_1$	6	51	$_2B_6$
V_{CC}	7	50	V_{CC}
A_1	8	49	$_2B_7$
A_2	9	48	$_2B_8$
A_3	10	47	$_2B_9$
GND	11	46	GND
A_4	12	45	$_2B_{10}$
A_5	13	44	$_2B_{11}$
A_6	14	43	$_2B_{12}$
A_7	15	42	$_1B_{12}$
A_8	16	41	$_1B_{11}$
A_9	17	40	$_1B_{10}$
GND	18	39	GND
A_{10}	19	38	$_1B_9$
A_{11}	20	37	$_1B_8$
A_{12}	21	36	$_1B_7$
V_{CC}	22	35	V_{CC}
$_1B_1$	23	34	$_1B_6$
$_1B_2$	24	33	$_1B_5$
GND	25	32	GND
$_1B_3$	26	31	$_1B_4$
NC	27	30	$\overline{CLKENA1}$
$\overline{SEL}$	28	29	CLK

SSOP/ TSSOP/ TVSOP
TOP VIEW

CAPACITANCE (T_A = +25°C, F = 1.0MHz)

Symbol	Parameter[1]	Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	5	7	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	7	9	pF
$C_{I/O}$	I/O Port Capacitance	V_{IN} = 0V	7	9	pF

NOTE:
1. As applicable to the device type.

ABSOLUTE MAXIMUM RATINGS[1]

Symbol	Description	Max	Unit
V_{TERM}[2]	Terminal Voltage with Respect to GND	–0.5 to +4.6	V
V_{TERM}[3]	Terminal Voltage with Respect to GND	–0.5 to V_{CC}+0.5	V
T_{STG}	Storage Temperature	–65 to +150	°C
I_{OUT}	DC Output Current	–50 to +50	mA
I_{IK}	Continuous Clamp Current, V_I < 0 or V_I > V_{CC}	±50	mA
I_{OK}	Continuous Clamp Current, V_O < 0	–50	mA
I_{CC} I_{SS}	Continuous Current through each V_{CC} or GND	±100	mA

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{CC} terminals.
3. All terminals except V_{CC}.

FUNCTION TABLES[1]

OUTPUT ENABLE

Inputs			Outputs	
CLK	$\overline{OEA}$	$\overline{OEBx}$	Ax	$_1Bx, _2Bx$
↑	H	H	Z	Z
↑	H	L	Z	Active
↑	L	H	Active	Z
↑	L	L	Active	Active

A-TO-B STORAGE ($\overline{OEB}$ = L)

Inputs				Outputs	
$\overline{CLKENA1}$	$\overline{CLKENA2}$	CLK	Ax	$_1Bx$	$_2Bx$
H	H	X	X	$_1B$[2]	$_2B$[2]
L	X	↑	L	L	X
L	X	↑	H	H	X
X	L	↑	L	X	L
X	L	↑	H	X	H

B-TO-A STORAGE ($\overline{OEA}$ = L)

Inputs				Outputs
CLK	$\overline{SEL}$	$_1Bx$	$_2Bx$	Ax
X	H	X	X	A[2]
X	L	X	X	A[2]
↑	H	L	X	L
↑	H	H	X	H
↑	L	X	L	L
↑	L	X	H	H

NOTES:
1. H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
   Z = High Impedance
   ↑ = LOW-to-HIGH transition
2. Output level before the indicated steady-state input conditions were established.

PIN DESCRIPTION

Pin Names	I/O	Description
Ax(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's Address/Data bus.[1]
1Bx(1:12)	I/O	Bidirectional Data Port 1B. Usually connected to the even path or even bank of memory.[1]
2Bx(1:12)	I/O	Bidirectional Data Port 2B. Usually connected to the odd path or odd bank of memory.[1]
CLK	I	Clock Input
$\overline{CLKENA1}$	I	Clock Enable Input for the A-1B Register. If $\overline{CLKENA1}$ is LOW during the rising edge of CLK, data will be clocked into register A-1B (Active LOW).
$\overline{CLKENA2}$	I	Clock Enable Input for the A-2B Register. If $\overline{CLKENA2}$ is LOW during the rising edge of CLK, data will be clocked into register A-2B (Active LOW).
$\overline{SEL}$	I	1B or 2B Port Selection. When HIGH during the rising edge of CLK, $\overline{SEL}$ enables data transfer from 1B Port to A Port. When LOW during the rising edge of CLK, $\overline{SEL}$ enables data transfer from 2B Port to A Port.
$\overline{OEA}$	I	Synchronous Output Enable for A Port (Active LOW)
$\overline{OEB1}$	I	Synchronous Output Enable for 1B Port (Active LOW)
$\overline{OEB2}$	I	Synchronous Output Enable for 2B Port (Active LOW)

NOTE:
1. These pins have "Bus-Hold". All other pins are standard inputs, outputs, or I/Os.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:
Operating Condition: T_A = –40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ.[1]	Max.	Unit
V_{IH}	Input HIGH Voltage Level	V_{CC} = 2.3V to 2.7V		1.7	—	—	V
		V_{CC} = 2.7V to 3.6V		2	—	—	
V_{IL}	Input LOW Voltage Level	V_{CC} = 2.3V to 2.7V		—	—	0.7	V
		V_{CC} = 2.7V to 3.6V		—	—	0.8	
I_{IH}	Input HIGH Current	V_{CC} = 3.6V	V_I = V_{CC}	—	—	±5	µA
I_{IL}	Input LOW Current	V_{CC} = 3.6V	V_I = GND	—	—	±5	µA
I_{OZH}	High Impedance Output Current	V_{CC} = 3.6V	V_O = V_{CC}	—	—	±10	µA
I_{OZL}	(3-State Output pins)		V_O = GND	—	—	±10	
V_{IK}	Clamp Diode Voltage	V_{CC} = 2.3V, I_{IN} = –18mA		—	–0.7	–1.2	V
V_H	Input Hysteresis	V_{CC} = 3.3V		—	100	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	V_{CC} = 3.6V V_{IN} = GND or V_{CC}		—	0.1	40	µA
ΔI_{CC}	Quiescent Power Supply Current Variation	One input at V_{CC} - 0.6V, other inputs at V_{CC} or GND		—	—	750	µA

NOTE:
1. Typical values are at V_{CC} = 3.3V, +25°C ambient.

BUS-HOLD CHARACTERISTICS

Symbol	Parameter[1]	Test Conditions		Min.	Typ.[2]	Max.	Unit
I_{BHH}	Bus-Hold Input Sustain Current	V_{CC} = 3V	V_I = 2V	– 75	—	—	µA
I_{BHL}			V_I = 0.8V	75	—	—	
I_{BHH}	Bus-Hold Input Sustain Current	V_{CC} = 2.3V	V_I = 1.7V	– 45	—	—	µA
I_{BHL}			V_I = 0.7V	45	—	—	
I_{BHHO}	Bus-Hold Input Overdrive Current	V_{CC} = 3.6V	V_I = 0 to 3.6V	—	—	±500	µA
I_{BHLO}							

NOTES:
1. Pins with Bus-Hold are identified in the pin description.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions[1]		Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = 2.3V to 3.6V	I_{OH} = – 0.1mA	V_{CC} – 0.2	—	V
		V_{CC} = 2.3V	I_{OH} = – 4mA	1.9	—	
			I_{OH} = – 6mA	1.7	—	
		V_{CC} = 2.7V	I_{OH} = – 4mA	2.2	—	
			I_{OH} = – 8mA	2	—	
		V_{CC} = 3V	I_{OH} = – 6mA	2.4	—	
			I_{OH} = – 12mA	2	—	
V_{OL}	Output LOW Voltage	V_{CC} = 2.3V to 3.6V	I_{OL} = 0.1mA	—	0.2	V
		V_{CC} = 2.3V	I_{OL} = 4mA	—	0.4	
			I_{OL} = 6mA	—	0.55	
		V_{CC} = 2.7V	I_{OL} = 4mA	—	0.4	
			I_{OL} = 8mA	—	0.6	
		V_{CC} = 3V	I_{OL} = 6mA	—	0.55	
			I_{OL} = 12mA	—	0.8	

NOTE:
1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. T_A = – 40°C to + 85°C.

OPERATING CHARACTERISTICS, T_A = 25°C

Symbol	Parameter	Test Conditions	V_{CC} = 2.5V ± 0.2V Typical	V_{CC} = 3.3V ± 0.3V Typical	Unit
C_{PD}	Power Dissipation Capacitance Outputs enabled	C_L = 0pF, f = 10Mhz	142	172	pF
C_{PD}	Power Dissipation Capacitance Outputs disabled		115	129	

SWITCHING CHARACTERISTICS[1]

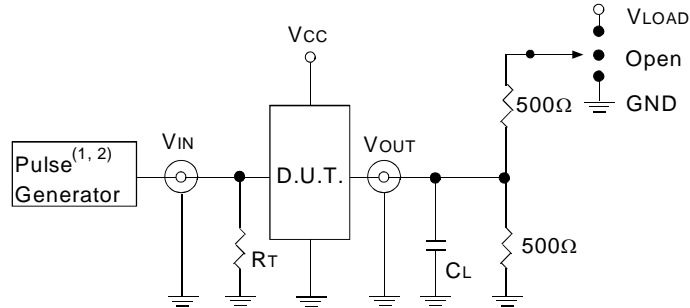| Symbol	Parameter	V_{CC} = 2.5V ± 0.2V		V_{CC} = 2.7V		V_{CC} = 3.3V ± 0.15V		V_{CC} = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
f_{CLOCK}	Clock Frequency	—	95	—	115	—	135	—	135	MHz
t_{PLH} t_{PHL}	Propagation Delay CLK to xBx	2.3	7.7	—	6.9	2.3	5	2.2	5.8	ns
t_{PLH} t_{PHL}	Propagation Delay CLK to Ax	1.9	6.4	—	5.8	2	4	2	5.2	ns
t_{PZH} t_{PZL}	Output Enable Time CLK to xBx	2.5	7.7	—	6.9	2.3	5	2.3	5.8	ns
t_{PZH} t_{PZL}	Output Enable Time CLK to Ax	2.2	6.7	—	6	2.1	4.3	2.1	5.3	ns
t_{PHZ} t_{PLZ}	Output Disable Time CLK to xBx	3.3	8.1	—	6.7	2.3	5.3	2.4	6	ns
t_{PHZ} t_{PLZ}	Output Disable Time CLK to Ax	2.7	8	—	6.2	2.2	5.4	2.1	6	ns
t_{SU}	Set-Up Time, Ax data before CLK↑	1.4	—	1.4	—	0.9	—	1	—	ns
t_{SU}	Set-Up Time, Bx data before CLK↑	1.6	—	1.5	—	1	—	1.1	—	ns
t_{SU}	Set-Up Time, $\overline{SEL}$ before CLK↑	0.8	—	1.1	—	1.3	—	1.3	—	ns
t_{SU}	Set-Up Time, $\overline{CLKENA1}$ or $\overline{CLKENA2}$ before CLK↑	0.8	—	1	—	0.7	—	0.8	—	ns
t_{SU}	Set-Up Time, $\overline{OEBx}$ or $\overline{OEA}$ before CLK↑	1.7	—	1.6	—	1.1	—	1.2	—	ns
t_{H}	Hold Time, Ax data after CLK↑	0.9	—	0.9	—	1.1	—	1.2	—	ns
t_{H}	Hold Time, Bx data after CLK↑	0.8	—	0.6	—	0.8	—	1	—	ns
t_{H}	Hold Time, $\overline{SEL}$ after CLK↑	1.1	—	0.8	—	1.6	—	1.7	—	ns
t_{H}	Hold Time, $\overline{CLKENA1}$ or $\overline{CLKENA2}$ after CLK↑	1.4	—	1	—	1.4	—	1.6	—	ns
t_{H}	Hold Time, $\overline{OEBx}$ or $\overline{OEA}$ after CLK↑	0.9	—	0.8	—	1	—	1.2	—	ns
t_{W}	Pulse Width, CLK HIGH or LOW	5.2	—	4.3	—	3.3	—	3.3	—	ns
$t_{SK(o)}$	Output Skew[2]	—	—	—	—	—	500	—	500	ps

NOTES:
1. See TEST CIRCUITS AND WAVEFORMS. T_A = – 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	Vcc[1] = 3.3V±0.3V	Vcc[1] = 2.7V	Vcc[2] = 2.5V±0.2V	Unit
V_{LOAD}	6	6	2 x Vcc	V
V_{IH}	2.7	2.7	Vcc	V
V_T	1.5	1.5	Vcc / 2	V
V_{LZ}	300	300	150	mV
V_{HZ}	300	300	150	mV
C_L	50	50	30	pF

Test Circuit for All Outputs

ALVC Link

DEFINITIONS:
C_L = Load capacitance: includes jig and probe capacitance.
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:
1. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V_{LOAD}
Disable High Enable High	GND
All Other Tests	Open
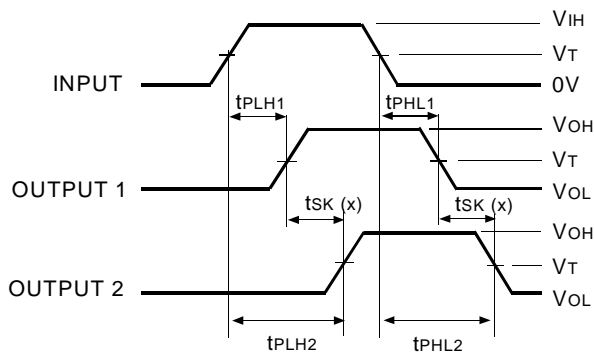
$t_{SK}(x) = |t_{PLH2} - t_{PLH1}|$ or $|t_{PHL2} - t_{PHL1}|$
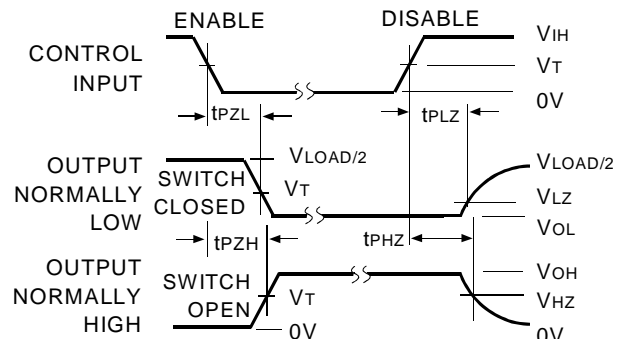
Output Skew - $t_{SK}(x)$

ALVC Link

NOTES:
1. For $t_{SK}(o)$ OUTPUT1 and OUTPUT2 are any two outputs.
2. For $t_{SK}(b)$ OUTPUT1 and OUTPUT2 are in the same bank.
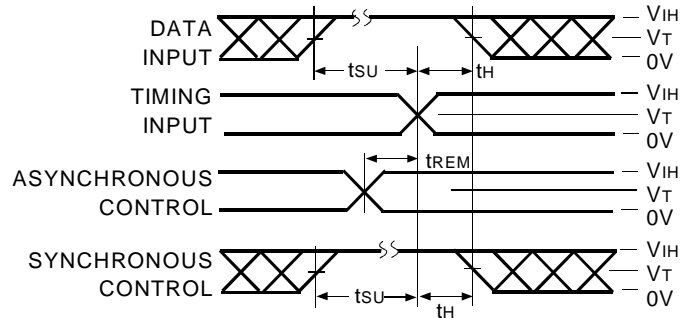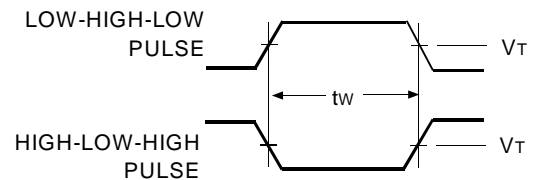

Propagation Delay

ALVC Link
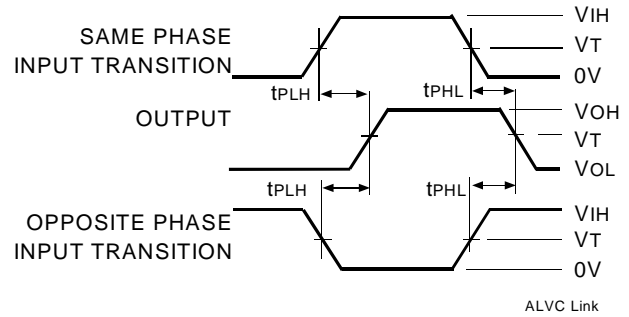
Enable and Disable Times

ALVC Link

NOTE:
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

Set-up, Hold, and Release Times

ALVC Link

Pulse Width

ALVC Link

ORDERING INFORMATION

IDT XX ALVC X XX XXX XX
Temp. Range Bus-Hold Family Device Type Package

PV   Shrink Small Outline Package
PA   Thin Shrink Small Outline Package
PF   Thin Very Small Outline Package

269A 12-Bit to 24-Bit Registered Bus Exchanger
      with 3-State Outputs

R162 Double-Density with Resistors, ±12mA

H   Bus-hold

74   − 40°C to +85°C